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EFS ID: 60604
Application ID: 10763859 
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HAVING REDUCED THICKNESS
First Named Inventor: TAE LEE
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Electronic Version v1.1
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Title of Invention	SEMICONDUCTOR PACKAGE HAVING REDUCED THICKNESS	
Application Number:	10/763859 	
Date:	2004-01-23	
First Named Applicant:	TAE HEON LEE	
Confirmation Number:	8528	
Attorney Docket Number:	AMKOR053G	
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Submitted by:	Elec. Sign.	Sign. Capacity
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney
Documents being submitted	Files	
us-ids	ids5-usidst.xml	
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	us-ids.xsl	
Comments		



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

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Attorney Docket Number:	AMKOR053G				
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents					
init	Cite.No.	Patent No.	Date	Patentee	Kind
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Signature

Examiner Name	Date